

PCN# 20130502001
Qualification of TI Malaysia as Additional Assembly Site
for UC3846N device
Change Notification / Sample Request

Date: 5/13/2013
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

20130502001
Attachment: 1

Products Affected:


The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
UC3846N	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20130502001			PCN Date:	05/13/2013									
Title:	Qualification of TI Malaysia as Additional Assembly Site for UC3846N device													
Customer Contact:	PCN Manager	Phone:	+1(214)480-6037	Dept:	Quality Services									
Proposed 1st Ship Date:	08/13/2013	Estimated Sample Availability:		Date Provided at Sample request										
Change Type:														
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Assembly Materials									
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification									
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process									
PCN Details														
Description of Change:														
<p>This PCN is to introduce TI Malaysia as an additional assembly site and 0.96mil Cu wire as an alternate assembly material for UC3846N device. Currently the device is only assembled at Carsem Malaysia with 1.3mil Au wire.</p> <p>Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.</p>														
Reason for Change:														
<p>Continuity of Supply</p> <ol style="list-style-type: none"> 1) To align with world technology trends and use wiring with enhanced mechanical and electrical properties 2) Maximize flexibility within our Assembly/Test production sites. 3) Cu is easier to obtain and stock 														
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):														
None														
Changes to product identification resulting from this PCN:														
<table border="1"> <tr> <td colspan="3">Assembly Site</td> </tr> <tr> <td>Carsem Malaysia</td> <td>Assembly Site Origin (22L)</td> <td>ASO: CRS</td> </tr> <tr> <td>TI Malaysia</td> <td>Assembly Site Origin (22L)</td> <td>ASO: MLA</td> </tr> </table>						Assembly Site			Carsem Malaysia	Assembly Site Origin (22L)	ASO: CRS	TI Malaysia	Assembly Site Origin (22L)	ASO: MLA
Assembly Site														
Carsem Malaysia	Assembly Site Origin (22L)	ASO: CRS												
TI Malaysia	Assembly Site Origin (22L)	ASO: MLA												

Sample product shipping label (not actual product label)


TEXAS INSTRUMENTS
 MADE IN: Malaysia
 2DC: 20:

MSL 2 /260C/1 YEAR	SEAL DT
MSL 1 /235C/UNLIM	03/29/04

 OPT:
 ITEM: 39
LBL: 5A (L)T0:1750


 G4



(1P) SN74LS07NSR
 (Q) 2000 (D) 0336
 (31T) LOT: 3959047MLA
 (4W) TKY (1T) 7523483SI2
 (P)
 (2P) REV: (V) 0033317
 (20L) CSO: SHE (21L) CCO:USA
 (22L) ASO: MLA (23L) ACO: MYS

Device Marking


 O
 {CUST1}
 YMLLLL

TI = TI LETTERS
 YM = YEAR MONTH DATE CODE
 LLLL = ASSEMBLY LOT CODE
S = ASSEMBLY SITE CODE
 O = PIN 1 INDICATOR

Topside Device marking:

Assembly site code for CRS = W

Assembly site code for TI-Malaysia = K

Product Affected:

UC3846N	UC3846NG4
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Qualification Data: Approved 05/11/2012

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qual Vehicle : SN74HC273N-P2

Package Construction Details

Assembly Site:	MLA	Mold Compound:	4042503
# Pins-Designator, Family:	20-N, PDIP	Mount Compound:	4042500
Leadframe (Finish, Base):	NiPdAu	Bond Wire:	0.96 Mil Dia., Cu

Qualification: Plan Test Results

Reliability Test	Conditions	Sample Size / Fail
Electrical Characterization	-	Pass
Manufacturability Qualification (MQ)		Pass
Temp Cycle, -65C/150C	500 Cycles	77/0
Autoclave	121C, 2 atm (96 Hrs)	77/0
High Temp Storage Bake	170C (420 Hrs)	77/0

Qual Vehicle 2 : TLC0838CN					
Package Construction Details					
Assembly Site:	MLA	Mold Compound:	4042503		
# Pins-Designator, Family:	20-N, PDIP	Mount Compound:	4042500		
Leadframe (Finish, Base):	NiPdAu	Bond Wire:	0.96 Mil Dia., Cu		
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results					
Reliability Test	Conditions		Sample Size / Fail		
Manufacturability Qualification (MQ)			Pass		
Temp Cycle, -65C/150C	500 Cycles		77/0		
Autoclave	121C, 2 atm (96 Hrs)		77/0		
High Temp Storage Bake	170C (420 Hrs)		77/0		
Qual Vehicle 3 : TLC5917IN					
Package Construction Details					
Assembly Site:	MLA	Mold Compound:	4042503		
# Pins-Designator, Family:	16-N, PDIP	Mount Compound:	4042500		
Leadframe (Finish, Base):	NiPdAu	Bond Wire:	0.96 Mil Dia., Cu		
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results					
Reliability Test	Conditions		Sample Size / Fail		
Manufacturability Qualification (MQ)			Pass		
Temp Cycle, -65C/150C	500 Cycles		77/0		
Autoclave	121C, 2 atm (96 Hrs)		77/0		
High Temp Storage Bake	170C (420 Hrs)		77/0		
Qual Vehicle 4 : ULN2003AN					
Package Construction Details					
Assembly Site:	MLA	Mold Compound:	4042503		
# Pins-Designator, Family:	16-N, PDIP	Mount Compound:	4042500		
Leadframe (Finish, Base):	NiPdAu	Bond Wire:	0.96 Mil Dia., Cu		
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results					
Reliability Test	Conditions		Sample Size / Fail		
Manufacturability Qualification (MQ)			Pass	Pass	Pass
Biased HAST	130C/85%RH (96 Hrs)		77/0	77/0	77/0

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com